



Elemental analysis of *Genesis* Silicon wafers

Munir Humayun Florida State University

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Flight SoS wafer fragment 50030 Results



- Mg and Fe determined by isotope dilution;
- Si determined by external standardization.
- Mg: 5.21 x $10^{12} \pm 1.2\%$ (2 σ) atoms
- Fe: 5.26 x $10^{12} \pm 1.0\%$ (2 σ) atoms
- $Fe/Mg_{atomic} = 1.01 \pm 1.6\% (2\sigma)$
- Si: 2.08 x $10^{18} \pm 5\%$ (2 σ) atoms
- Area removed=2.47-2.76 cm², assuming a thickness of the Si layer of 170-190 nm, vs. geometrically measured area =2.76 cm².

Fluence:

Mg: 1.99 x $10^{12} \pm 5\%$ (2 σ) atoms/cm²

Fe: 2.01 x $10^{12} \pm 5\%$ (2 σ)



Cleaning sequence for Si

• Four steps of hot aqua regia attack (~88 hours), with 1 hour ultrasonic cleaning between steps, produced a successively diminishing blank with Mg, Fe < SW values.

• RCA cleaning step reduced many contaminants.

Time (hours)

aqua regia a	aqua regia b	aqua regia c	aqua regia d						
• SC-1: $NH_4OH:H_2O_2:H_2O$, 1:1:5, 10 mins. Hot • HF:H2O, 1:50, 10 secs • SC-2: HCI:H_2O_2:H_2O, 1:1:6, 10 mins. Hot • HF:H2O, 1:50, 10 secs • 4 steps: 10-15 secs of HF:HNO_3:H_2O @ room T released 4, 5, 7, 8 µm-equivalents of Si									

Chemical systematics in first aqua regia leach step of Si wafers



- **Ge/Si~** 0.2
- Fe/Cr~ 4 (stainless steel)
- Mg correlates with Na, Ca, and less with Ti, Si, and not with Fe.



Comparison of chemical abundances in first



Post HF attack, reflected light images of Si 60496











Summary

- 1. Si wafers proved more intractable to our cleaning procedures than SOS wafers.
- 2. Large amounts of post-crash contaminants are leached in hot aqua regia steps, but some contaminants appear to be "sheltered" from acid attack.
- 3. HF-HNO₃ releases further contaminants, which indicates possibly located in melted Si.
- 4. Mg recovered was 2xSW, Fe ~ 4xSW in 60496-2.

Isotope fractionation of Solar Wind elements as a tracer of SW abundances

Bochsler (2000) predicts a light isotope enrichment of ~12‰/m.u. for Mg which could be a powerful tracer of SW Mg. Even a 100% contamination of SW Mg would retain an isotope enrichment of ~6‰/m.u. This is best done in unspiked runs.



Figure 5. Expected isotope fractionation factors associated with He/H depletion factors. For instance, a depletion of He/H to 30% of its normal value in the equatorial streamer belt implies an enhancement of the ${}^{28}\text{Si}^{12+}/{}^{30}\text{Si}^{12+}$ ratio up to 1.7% over its normal coronal value.

Isotope ratio precision with MC-ICP-MS using ~80 pg Mg 10 δ²⁶Mg (‱) +1 2 ppb Mg 10 ppb Mg 0.1 1.E+12 1.E + 111.E+13 1.E + 14No. of atoms

Mg isotopic compositions of UTTR Mg, chondrites, terrestrial



1. Consortium studies of Genesis flight wafer 60472: a proposal

Si wafer 60472 is a 0.3 cm2 wafer that has been cleaned by our acid procedure, with analyzed elemental abundances.

 SEM examination of residual contaminants.
TR-SXRF or TOF-SIMS study of surface layer.
Focused cleaning effort at FSU.
Mg isotopic analysis of extracted Mg (MC-ICP-MS) and elemental composition by isotope dilution (Element XR) on separate aliquots.
Return to SoS wafers for combined elemental and isotopic analyses of Mg (Fe, etc.)



Checking ²⁶Mg-⁵⁷Fe Spike

	BHVO-1	BHVO-2	BCR- 1	BIR-1	NIST SRM	Tagish Lake	
Mg(%) literature	4.36	4.36	2.15	5.85	612		
Mg(%)	4.58	4.51	2.14	5.88			
relative	5.0%	3.4%	-0.3%	0.5%			
Fe(%) literature	8.55	8.60	9.38	7.09			
Fe(%) measured	8.71	8.86	9.36	8.06			
relative	1.8%	3.0%	-0.2%	1.9%			
Fe/Mg literature	1.96	1.97	4.37	1.35	0.727	2.02	
Fe/Mg	1.90	1.97	4.37	1.37	0.727	2.11	
measured	±0.7%	±0.7%	±0.8	±0.7	±0.7%	±0.9	
(20)tive	-3%	0%	%	%	0%	‰	

Step-Cleaning Procedure:

- 1. Two sequential 15-46 hour steps with hot aqua regia (HCI:HNO₃:H₂O 3:1:1) attack.
- 2. RCA clean:
 - ultrasonication in 1 H_2O_2 : 0.5 NH_4OH : 10 H_2O ;
 - ultrasonication in 0.7 HCI : 1 HF : 100 H₂O;
- 3. Two further 15-hour steps of hot aqua regia $(HCI:HNO_3 3:1)$.
- 4. Quick rinse with 1:50 HF:MQ water

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Post HF attack, reflected light mosaic of 60496 rear



Post HF attack, reflected light image of 60496



Scale: 800 µm

Post HF attack, reflected light image of 60496



Scale: 800 µm

Post HF attack, reflected light image of 60496 front



Scale: 800 µm